Am29700 • Am29701 Noninverting Schottky 64-Bit RAM

Refer to Am27S06 • Am27S07 Bipolar Memory RAM Product Specification

The Am29700 is replaced by the Am27S06 (open collector).

The Am29701 is replaced by the Am27S07 (three-state).

Am27LS06 • Am27LS07

Low Power, Noninverting 64-Bit Bipolar RAM

DISTINCTIVE CHARACTERISTICS

- Fully decoded 16-word x 4-bit low power Schottky RAMs
- Ultra-low power: I_{CC} typically 30mA
- High-speed: Address access time typically 40ns
- Internal ECL circuitry for optimum speed/power performance over voltage and temperature
- Output preconditioned during write to eliminate the write recovery glitch
- Available with three-state outputs (Am27LS07) or with open collector outputs (Am27LS06)
- 100% MIL-STD-883 assurance testing
- Electrically tested and optically inspected die for the assemblers of hybrid products
- Guaranteed to INT-STD-123

FUNCTIONAL DESCRIPTION

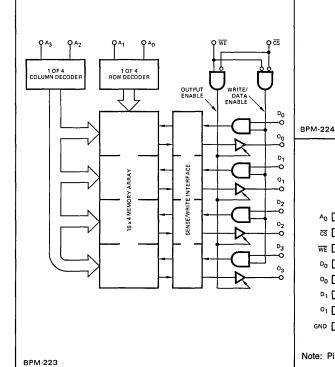
The Am27LS06 and Am27LS07 are 64-bit RAMs built using Schottky diode clamped transistors in conjunction with internal ECL circuitry and are ideal for use in scratch pad and high-speed buffer memory applications. Each memory is organized as a fully decoded 16-word memory of 4 bits per word. Easy memory expansion is provided by an active LOW chip select (CS) input and open collector OR tieable outputs (Am27LS06) or three-state outputs (Am27LS07). Chip selection for large memory systems can be controlled by active LOW output decoders such as the Am74LS189.

An active LOW Write line \overline{WE} controls the writing/reading operation of the memory. When the chip select and write lines are LOW the information on the four data inputs D_0 to D_0 is written into the addressed memory word and preconditions the output circuitry so that correct data is present at the outputs when the write cycle is complete. This preconditioning operation insures minimum write recovery times by eliminating the "write recovery glitch".

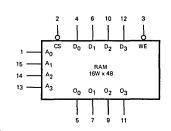
Reading is performed with the chip select line LOW and the write line HIGH. The information stored in the addressed word is read out on the four noninverting outputs O₀ to O₃.

During the writing operation or when the chip select line is HIGH the four outputs of the memory go to an inactive high impedance state.

LOGIC BLOCK DIAGRAM



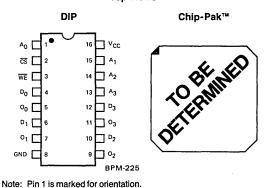
LOGIC SYMBOL



V_{CC} = Pin 16 GND = Pin 8

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CONNECTION DIAGRAMS Top Views



Chip-Pak is a trademark of Advanced Micro Devices, Inc.

MAXIMUM RATINGS (Above which the useful life may be impaired)

| Storage Temperature | −65 to +150°C |
|--|------------------------------|
| Temperature (Ambient) Under Bias | −55 to +125°C |
| Supply Voltage to Ground Potential (Pin 16 to Pin 8) | -0.5 to +7V |
| DC Voltage Applied to Outputs for High Output State | −0.5V to V _{CC} max |
| DC Input Voltage | -0.5 to +5.5V |
| Output Current, Into Outputs | 20mA |
| DC Input Current | -30 to +5.0mA |

OPERATING RANGE

| Range | Vcc | Ambient Temperature |
|-------|---------------|------------------------|
| COM'L | 4.75 to 5.25V | 0 to +75°C |
| MIL | 4.5 to 5.5V | -55 to +125°C |

FUNCTION TABLE

| lnı | out | | Data Output | | | |
|------|---------------|----------|------------------------------|--|--|--|
| cs | WE | Function | Status O ₀₋₃ | | | |
| Low | Low | Write | Output Disabled | | | |
| Low | High | Read | Selected Word (Not Inverted) | | | |
| High | Don't Care | Deselect | Output Disabled | | | |

ELECTRICAL CHARACTERISTICS OVER OPERATING RANGE (Unless Otherwise Noted)

| Parameters | Description | DC Test Conditions | | | | Typ (Note 1) | Max | Units |
|---------------------------------------|---------------------------------------|--|--------------------------|-------|--------|-----------------|--------|-------|
| VoH | | V _{CC} = MIN, | I _{OH} = -5.2mA | COM'L | 2.4 | 3.6 | | Volts |
| (Am27LS07 only) | Output HIGH Voltage | $V_{IN} = V_{IH}$ or V_{IL} | I _{OH} = -2.0mA | MIL | 2.4 | | | |
| V _{OL} | Output LOW Voltage | V _{CC} = MIN, | I _{OL} = 8.0mA | | 0 | 0.280 | 0.45 | Volts |
| -OL | · · · · · · · · · · · · · · · · · · · | $V_{IN} = V_{IH}$ or V_{IL} | I _{OL} = 10mA | | | 0.310 | 0.5 | |
| V _{IH} | Input HIGH Level | Guaranteed input logical HIGH voltage for all inputs (Note 2) | | | 2.0 | | | Volts |
| V _{IL} | Input LOW Level | Guaranteed input logical LOW voltage for all inputs (Note 2) | | | | | 0.8 | Volts |
| կլ | Input LOW Current | $V_{CC} = MAX$, \overline{WE} , D_0 - D_3 , A_0 - A_3 | | | -0.015 | -0.250 | mA | |
| 12 | $V_{IN} = 0.40V$ | | CS | | | -0.030 | -0.250 | 1 |
| lн | Input HIGH Current | $V_{CC} = MAX, V_{IN} = 2.4V$ | = 2.4V | | | 0 | 10 | μА |
| I _{SC} (Am27LS07 only) | Output Short Circuit Current | V _{CC} = MAX, V _{OUT} = 0.0V | | | 20 | -45 | -90 | mA |
| I _{CC} Power Supply Current | | All inputs = GND COM'L | | | 30 | 35 | mA | |
| .00 | . oner supply surrout | V _{CC} = MAX | | MIL | | 30 | 38 | 1 ""` |
| V _{CL} | Input Clamp Voltage | V _{CC} = MIN, I _{IN} = -18mA | | | | -0.850 | -1.2 | Volts |
| I _{CEX} | Output Leakage Current | $V_{\overline{CS}} = V_{IH} \text{ or } V_{\overline{WE}} = V_{IL}$ $V_{OUT} = 2.4V$ | Am27LS06/07 | | | 0 | 40 | μА |
| CEX Conput Learnage Current | | VCS = VIH or VWE = VIL VOUT = 0.4V, VCC = MAX | Am27LS07 | | -40 | 0 | | μА |

Notes: 1. Typical limits are at $V_{CC} = 5.0V$ and $T_A = 25^{\circ}C$.

These are absolute voltages with respect to device ground pin and include all overshoots and undershoots due to system and/or tester noise.Do not attempt to test these values without suitable equipment.

SWITCHING CHARACTERISTICS OVER OPERATING RANGE (Unless Otherwise Noted)

| | | | AC | Тур | COM'L | | MIL | | | |
|------------------------------------|--|------------|--------------------------------------|----------|-------|-----|-----|-----|-------|--|
| Parameters | Description | | Test Conditions | (Note 1) | Min | Max | Min | Max | Units | |
| t _{PLH} (A) | Delay from Address to Output | See Fig. 2 | | 40 | | 55 | | 65 | | |
| t _{PHL} (A) | Delay from Address to Output | See rig. 2 | | 40 | | 55 | | 65 | ns | |
| t _{PZH} (CS) | Delay from Chip Select to Active | See Fig. 2 | | 18 | | 30 | | 35 | ns | |
| t _{PZL} (CS) | Output and Correct Data | 366 Fig. 2 | | 10 | | 30 | | 35 | ns | |
| t _{PZH} (WE) | Delay from Write Enable (HIGH) to Active Output and Correct Data | See Fig. 1 | | 18 | | 30 | | 35 | ns | |
| t _{PZL} (WE) | (Write Recovery - See Note 2) | | | | | | | | | |
| t _S (A) | Setup Time Address (Prior to Initiation of Write) | See Fig. 1 | Figure 3 Test Load | -17 | 0 | | 0 | | ns | |
| t _h (A) | Hold Time Address (After Termination of Write) | See Fig. 1 | and Figure 4 for Input Waveform | -6 | 0 | | 0 | | ns | |
| t _s (DI) | Setup Time Data Input (Prior to Termination of Write) | See Fig. 1 | Characteristics See Notes 3 and 4 | 16 | 45 | | 55 | | ns | |
| t _h (DI) | Hold Time Data Input (After Termination of Write) | See Fig. 1 | | -8 | 0 | | 0 | | ns | |
| t _{pw} (WE) | Min Write Enable Pulse Width to Insure Write | See Fig. 1 | | 25 | 45 | | 55 | | ns | |
| t _{PHZ} (CS) | Delay from Chip Select to | See Fig. 2 | | 18 | | 30 | | 35 | ns | |
| t _{PLZ} (CS) | Inactive Output (HI-Z) | 366 Fig. 2 | | _ '6 | | 30 | | 35 | l lis | |
| t _{PLZ} (WE) | Delay from Write Enable (LOW) | See Fig. 1 | | 18 | | 30 | | 35 | ns | |
| t _{PHZ} (WE) | to Inactive Output (HI-Z) | | | | | | | | | |

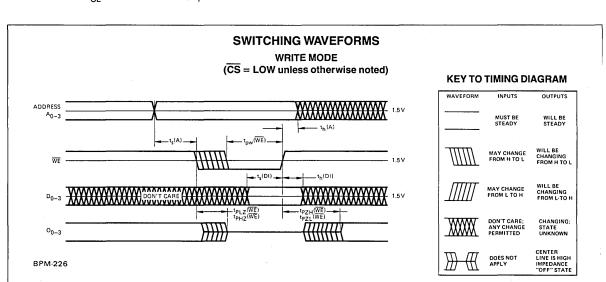
Notes: 1. Typical limits are at $V_{CC} = 5.0V$ and $T_A = 25^{\circ}C$.

- Output is preconditioned to data in (noninverted) during write to insure correct data is present on all outputs when write is terminated. (No write recovery glitch.)
- 3. For open collector Am27LS06, all delays from Write Enable (WE) or Chip Select (CS) inputs to the Data Output (O₀-O₃), t_{PLZ}(WE), t_{PLZ}(CS), t_{PLZ}(WE) and t_{PZ}(CS) are measured with St. closed and C₁ = 30pE and with both the input and output timing referenced to 1.5V.
- t_{PZL}(WE) and t_{PZL}(CS) are measured with S₁ closed and C_L = 30pF and with both the input and output timing referenced to 1.5V.

 4. For 3-state output Am27LS07, t_{PZH}(WE) and t_{PZH}(CS) are measured with S₁ open, C_L = 30pF and with both the input and output timing referenced to 1.5V.

 t_{PLZ}(WE) and t_{PLZ}(CS) are measured with S₁ closed, C_L = 30pF and with both the input and output timing referenced to 1.5V.

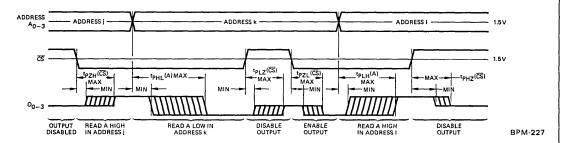
 t_{PLZ}(WE) and t_{PLZ}(CS) are measured with S₁ open and C_L ≤5pF and are measured between the 1.5V level on the input to the V_{OH} − 500mV level on the output. t_{PLZ}(WE) and t_{PLZ}(CS) are measured with S₁ closed and C_L ≤ 5pF and are measured between the 1.5V level on the input and the V_{OI} + 500mV level on the output.



Write Cycle Timing. The cycle is initiated by an address change. After $t_s(A)$ min, the write enable may begin. The chip select must also be LOW for writing. Following the write pulse, $t_h(A)$ min must be allowed before the address may be changed again. The output will be inactive (floating for the Am27LS07) while the write enable is LOW or the chip select is HIGH.

Figure 1.

SWITCHING WAVEFORMS (Cont.) READ MODE



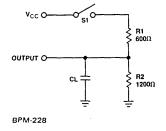
Switching delays from address and chip select inputs to the data output. For the Am27LS07, disabled output is "OFF", represented by a single center line. For the Am27LS06, a disabled output is HIGH.

Figure 2.

AC TEST LOAD AND WAVEFORM

AC TEST LOAD

INPUT PULSES



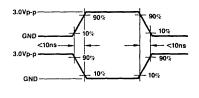


Figure 3.

Figure 4.

BPM-229

See notes 2, 3 and 4 of Switching Characteristics.

ORDERING INFORMATION

| | Order | Code | Package | Screening | Operating | |
|--------------------|---|---|--|--|-------------------|--|
| Speed Selection | Open Collector Three-State | | Type (Note 1) | Flow Code (Note 2) | Range (Note 3) | |
| 55ns | AM27LS06PC AM27LS06PCB AM27LS06DC AM27LS06DCB AM27LS06LC AM27LS06LC | AM27LS07PC AM27LS07PCB AM27LS07DC AM27LS07DCB AM27LS07LC AM27LS07LC | P-16-1 P-16-1 D-16-1 D-16-1 Consult Factory Consult Factory | C-1 B-1 C-1 B-1 C-1 B-1 | COM'L | |
| 65ns | AM27LS06DM AM27LS06DMB AM27LS06FM AM27LS06FMB AM27LS06LM AM27LS06LMB | AM27LS07DM AM27LS07DMB AM27LS07FM AM27LS07FMB AM27LS07LM AM27LS07LMB | D-16-1 D-16-1 F-16-1 F-16-1 Consult Factory Consult Factory | C-3 B-3 C-3 B-3 C-3 B-3 | MIL | |

Notes: 1. P = Molded DIP, D = Hermetic DIP, L = Chip-Pak, F = Cerpak. Number following letter is number of leads.

- Levels C-1 and C-3 conform to MIL-STD-883, Class C. Levels B-1 and B-3 conform to MIL-STD-883, Class B.
- 3. See Operating Range Table.